



CSP-62 Lead Free RoHS Profile

Total Mass of the Unit specified (g):	Product / Component Description	Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass (mg)	PPM	Additional Information
0.043	62 Ball CSP	IC Chip	Silicon doped with aluminium	Silicon (Si)	7440-21-3	30.113049	705,582	
		IC Chip	Silicon doped with aluminium	Aluminium (Al)	7429-90-5	0.017994	422	
		Metalization	UBM	Aluminium (Al)	7429-90-5	0.011175	262	
		Metalization	UBM	Nickel (Ni)	7440-02-0	0.005588	131	
		Metalization	UBM	Vanadium (V)	7440-62-2	0.005588	131	
		Metalization	UBM	Copper (Cu)	7440-50-8	0.044512	1,043	
		Metalization	BCB			0.067620	1,584	Cyclotene 4022-35
		IC Solderball	Solderball	Tin (Sn)	7440-31-5	11.854310	277,760	
		IC Solderball	Solderball	Silver (Ag)	7440-22-4	0.496449	11,632	
		IC Solderball	Solderball	Copper (Cu)	7440-50-8	0.062000	1,453	

Total mass (mg)	42.678
-----------------	--------